

REMARKS

Favorable reconsideration of this application as presently amended and in light of the following discussion is respectfully requested.

Claims 1-18 and 20 are pending in the present application with Claims 9-14, 16, 17, and 20 withdrawn from consideration. Claim 1 is amended by the present amendment.

In the outstanding Office Action, the drawings were objected to; Claims 1-8, 15, and 18 were rejected under 35 U.S.C. § 112, second paragraph; and Claims 1-8, 15, and 18 were rejected under 35 U.S.C. § 103(a) as unpatentable over Saito (Japanese Patent No. 63-166,254) in view of Honda et al. (U.S. Patent No. 6,849,805 (B2, herein "Honda").

Applicants thank the examiner for the courtesy of an interview extended to Applicants' representative on December 11, 2006. During the interview, the differences between the claims and the applied art were discussed. Further, clarifying claim amendments, similar to those presented herewith, were also discussed. The examiner indicated that he would further review the amended claims in view of a filed response. Arguments presented during the interview are reiterated below.

Regarding the objections to the drawings and the rejection of Claims 1-8, 15, and 18 under 35 U.S.C. § 112, second paragraph, the feature "each of said leads being joined to a heat sink or located near the heat sink in said plastic package" has been deleted from Claim 1. No new matter has been added. Accordingly, it is respectfully requested the objection to the drawings and the rejection under 35 U.S.C. § 112, second paragraph of the claims be withdrawn.

In view of the outstanding rejection of the claims on the merits, independent Claim 1 has been amended to more clearly recite the structure of a gap-controlling means. The claim amendment finds support in the specification, for example in Figures 1A-D and their corresponding description in the specification. No new matter has been added.

Briefly recapitulating, amended Claim 1 is directed to a semiconductor device of an insertion-mount-type that includes, *inter alia*, a plastic package and a plurality of leads. Some of the leads are formed as gap-controlling leads provided with a gap-controlling means to keep a gap between a semiconductor device and an external electric member constant when the leads of the semiconductor device are inserted into a lead-inserting portion of the external electric member. The gap-controlling means has a side surface configured to contact the external electric member but not enter the lead-inserting portion when a third lead portion is inserted into the lead-inserting portion.

In other words, the claimed semiconductor device of the insertion-mount-type as shown in Figure 2B, has the gap-controlling means 9 with a side surface that contacts the external electric member 25, but the side surface of the gap-controlling means 9 is configured to not enter into the lead-inserting portion 26 of the external electric member 25.

Turning to the applied art, Saito shows in Figures 3 and 4 that a lead 2 has a portion 4 that is inserted into an electric external member 21. Saito, also shows a tapered region (between reference signs 4 and 6) that is asserted by the outstanding Office Action to correspond to the claimed gap-controlling means.

However, the tapered portion of Saito does not have any side surface that contacts the external electric member 21. In this respect, it is noted that the tapered portion of Saito might have a line (but not a surface) in contact with the external electric member 21. In addition, a portion of the tapered portion of Saito would enter the hole 22 of the external electric member 21 when the lead 4 is inserted into the hole 22 because of the tapered nature of the tapered portion.

The outstanding Office Action relies on Honda for teaching leads being joined to a heat sink or located in the heat sink. However, Honda does not cure the deficiencies of Saito discussed above.

Accordingly, it is respectfully submitted that independent Claim 1 and each of the claims depending therefrom patentably distinguish over Saito and Honda, either alone or in combination.

Consequently, in light of the above discussion and in view of the present amendment, the present application is believed to be in condition for allowance and an early and favorable action to that effect is respectfully requested.

Respectfully submitted,

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